

General Description

The WSP8205 is the highest performance trench N-ch MOSFET with extreme high cell density , which provide excellent RDSON and gate charge for most of the small power switching and load switch applications.

The WSP8205 meet the RoHS and Green Product requirement with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent Cdv/dt effect decline
- Green Device Available

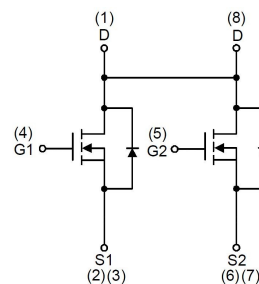
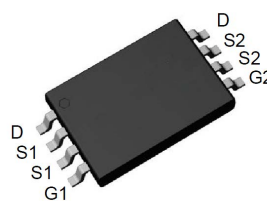
Product Summary

BVDSS	RDSON	ID
20V	20mΩ	6.0A

Applications

- High Frequency Point-of-Load Synchronous
Small power switching for MB/NB/UMPC/VGA
- Networking DC-DC Power System

TSSOP-8 Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	20	V
V_{GS}	Gate-Source Voltage	± 12	V
$I_D@T_c=25^{\circ}C$	Continuous Drain Current, $V_{GS} @ 4.5V^1$	6.0	A
$I_D@T_c=70^{\circ}C$	Continuous Drain Current, $V_{GS} @ 4.5V^1$	5.2	A
I_{DM}	Pulsed Drain Current ²	20	A
$P_D@T_A=25^{\circ}C$	Total Power Dissipation ³	1.25	W
T_{STG}	Storage Temperature Range	-55 to 150	$^{\circ}C$
T_J	Operating Junction Temperature Range	-55 to 150	$^{\circ}C$

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient ¹	---	100	$^{\circ}C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	---	70	$^{\circ}C/W$

Electrical Characteristics ($T_J=25^{\circ}\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	20	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	BVDSS Temperature Coefficient	Reference to 25°C , $I_D=1\text{mA}$	---	0.022	---	V/ $^{\circ}\text{C}$
$R_{DS(ON)}$	Static Drain-Source On-Resistance ²	$V_{GS}=10V, I_D=6A$	16	20	27	m Ω
		$V_{GS}=4.5V, I_D=4A$	19	23	30	
		$V_{GS}=3.1V, I_D=4A$	22	27	35	
		$V_{GS}=2.5V, I_D=4A$	25	30	39	
		$V_{GS}=1.8V, I_D=2A$	32	42	55	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	0.4	0.7	1.0	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	-2.33	---	mV/ $^{\circ}\text{C}$
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=16V, V_{GS}=0V, T_J=25^{\circ}\text{C}$	---	---	1	μA
		$V_{DS}=16V, V_{GS}=0V, T_J=55^{\circ}\text{C}$	---	---	5	
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 12V, V_{DS}=0V$	---	---	± 100	nA
g_{fs}	Forward Transconductance	$V_{DS}=5V, I_D=5A$	---	25	---	S
R_g	Gate Resistance	$V_{DS}=0V, V_{GS}=0V, f=1\text{MHz}$	---	4	---	Ω
Q_g	Total Gate Charge (4.5V)	$V_{DS}=10V, V_{GS}=4.5V, I_D=6A$	---	8.8	11.9	nC
Q_{gs}	Gate-Source Charge		---	0.8	2.0	
Q_{gd}	Gate-Drain Charge		---	3.3	3.2	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=10V, V_{GEN}=4.5V, R_G=6\Omega, I_D=1A, R_L=10\Omega.$	---	5	10	ns
T_r	Rise Time		---	15	26	
$T_{d(off)}$	Turn-Off Delay Time		---	30	55	
T_f	Fall Time		---	5	10	
C_{iss}	Input Capacitance	$V_{DS}=10V, V_{GS}=0V, f=1\text{MHz}$	---	550	---	pF
C_{oss}	Output Capacitance		---	100	---	
C_{rss}	Reverse Transfer Capacitance		---	85	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current ^{1,4}	$V_G=V_D=0V$, Force Current	---	---	1.5	A
I_{SM}	Pulsed Source Current ^{2,4}		---	---	20	A
V_{SD}	Diode Forward Voltage ²	$V_{GS}=0V, I_S=1.5A, T_J=25^{\circ}\text{C}$	---	---	1.3	V
t_{rr}	Reverse Recovery Time	$I_F=6A, di/dt=100A/\mu s, T_J=25^{\circ}\text{C}$	---	15	---	nS
Q_{rr}	Reverse Recovery Charge		---	7	---	nC

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 20Z copper, $t \leq 10\text{sec}$.
- 2.The data tested by pulsed, pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
- 3.The power dissipation is limited by 150°C junction temperature
- 4.The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.

Typical Characteristics

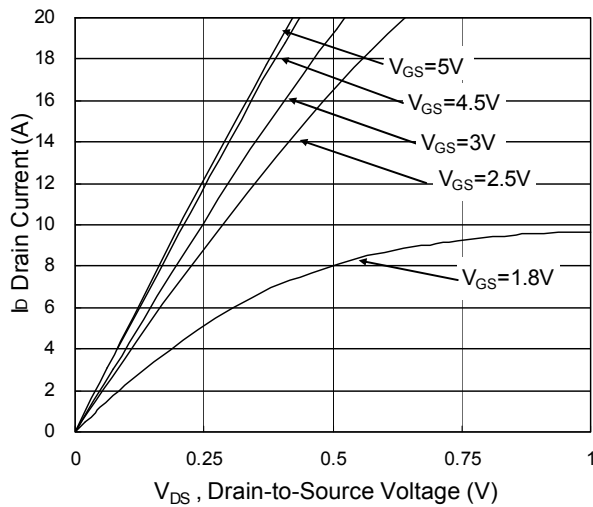
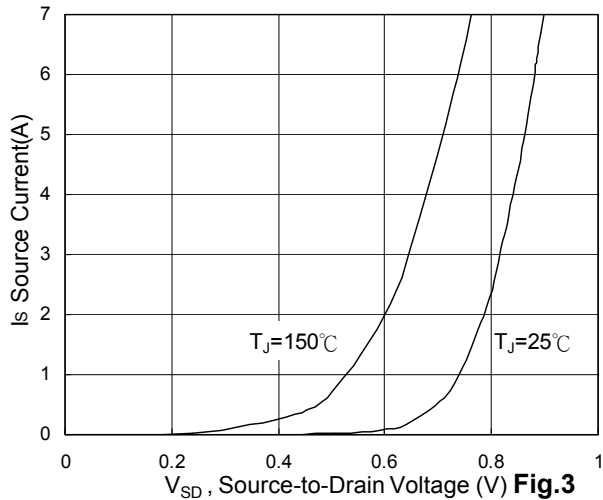


Fig.1 Typical Output Characteristics



Forward Characteristics Of Reverse

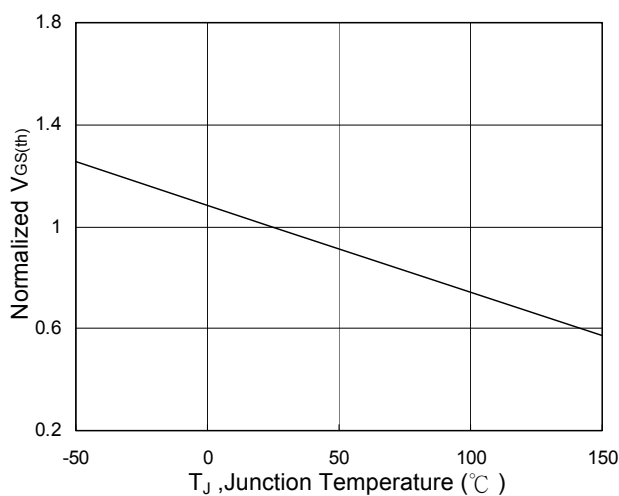


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

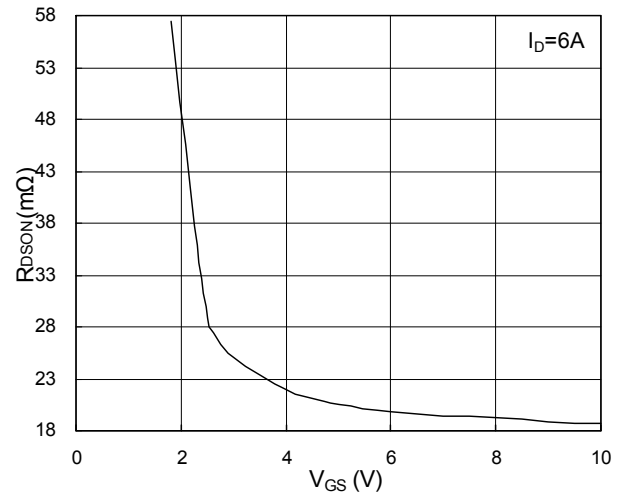


Fig.2 On-Resistance vs. Gate-Source

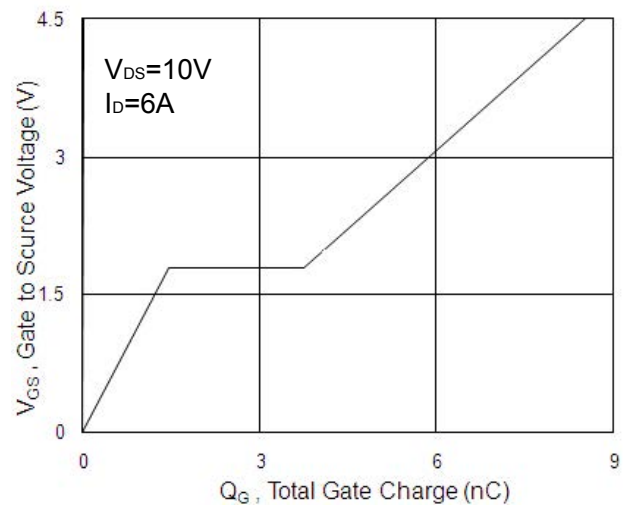


Fig.4 Gate-Charge Characteristics

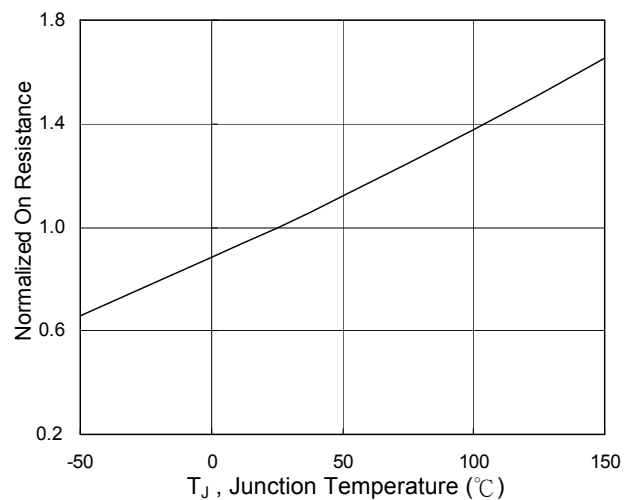


Fig.6 Normalized $R_{DS(on)}$ vs. T_J

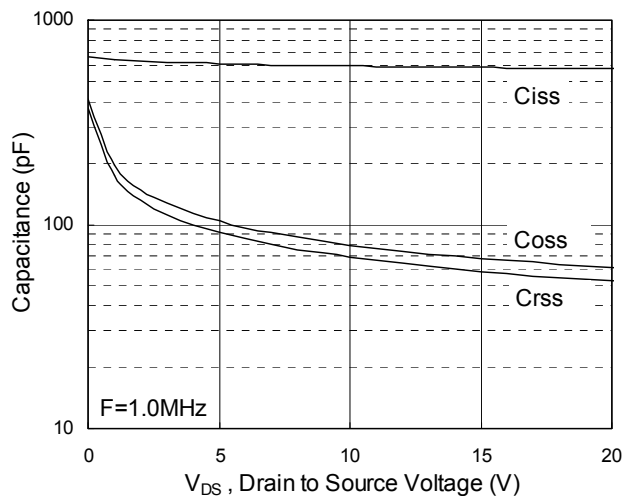


Fig.7 Capacitance

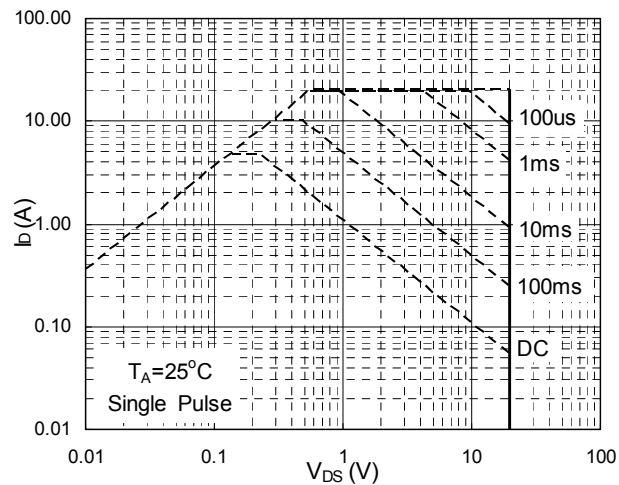


Fig.8 Safe Operating Area

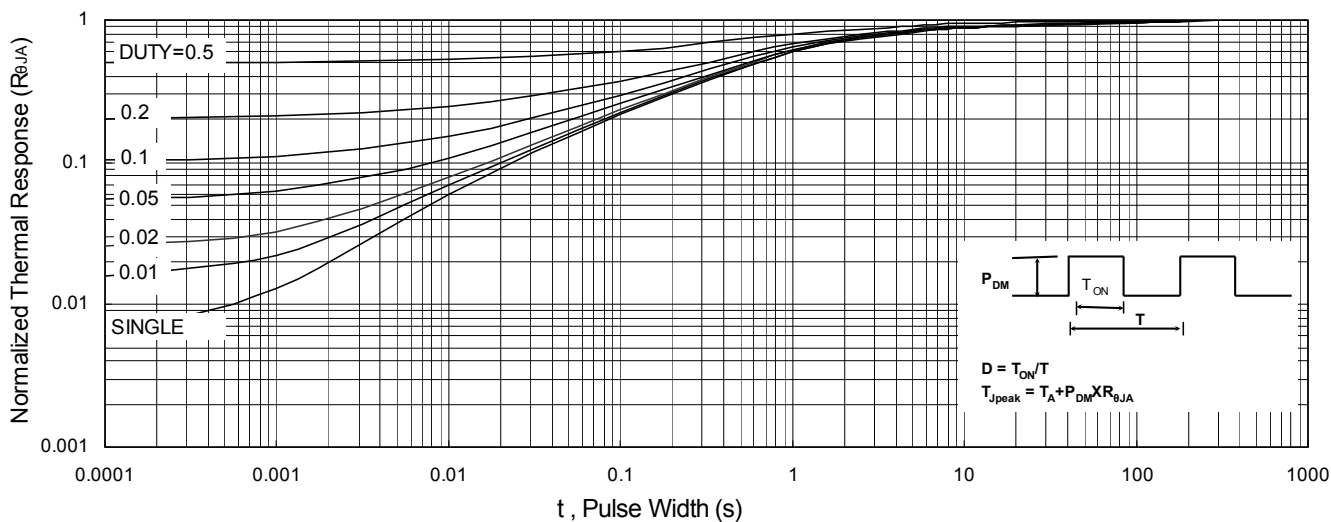


Fig.9 Normalized Maximum Transient Thermal Impedance

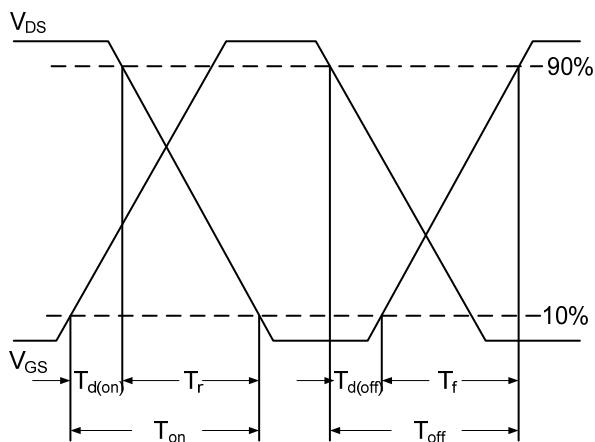


Fig.10 Switching Time Waveform

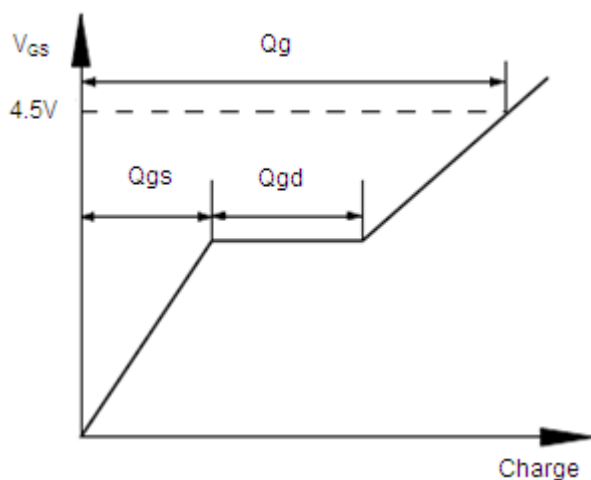


Fig.11 Gate Charge Waveform

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